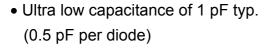
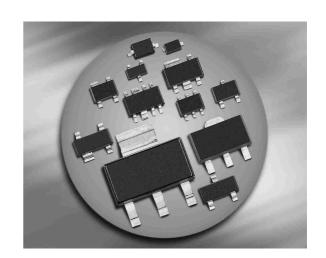


RF ESD Protection Diodes

 ESD / transient protection of RF antenna / interfaces or ultra high speed data lines acc. to: IEC61000-4-2 (ESD): ± 20 kV (contact) IEC61000-4-4 (EFT): 40 A (5/50 ns) IEC61000-4-5 (surge): 10 A (8/20 μs)



- Low clamping voltage
- Pb-free (ROHS compliant) package



Applications in anti-parallel configuration

 For low RF signal levels without superimposed DC voltage: e.g. GPS, WLAN, Bluetooth

Applications in rail-to-rail configuration

 For high RF signal levels or low RF signal levels with superimposed DC voltage: e.g. HDMI, S-ATA, Gbit Ethernet



ESD1P0RFW

ESD1P0RFS





Туре	Package	Configuration	Marking
ESD1P0RFS	SOT363	2 channels	E6s
ESD1P0RFW	SOT323	1 channel	E6s



Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾	V_{ESD}	20	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I_{pp}	10	Α
Operating temperature range	T_{op}	-55150	°C
Storage temperature	$T_{ m stg}$	-65150	

Electrical Characteristics at T_{Δ} = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
Characteristics					
Reverse working voltage ³⁾	V_{RWM}	-	-	70	V
Reverse current	I _R	-	-	100	nA
<i>V</i> _R = 70 V					
Forward clamping voltage ²⁾	V _{FC}				V
$I_{PP} = 3 \text{ A}, t_p = 8/20 \mu\text{s}$		_	4	7	
$I_{PP} = 10 \text{ A}, t_p = 8/20 \mu\text{s}$		-	12	15	
Line capacitance ⁴⁾	C _T				pF
$V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$		_	1	1.5	
V_{R} = 0 V, f = 1 MHz, for Application example 4		-	0.5	0.75	
Series inductance (per diode)	L _S				nH
SOT323		-	1.4	_	
SOT363		-	1.6	_	

¹V_{ESD} according to IEC61000-4-2, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

 $^{^2}I_{\mbox{\footnotesize pp}}$ according to IEC61000-4-5, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

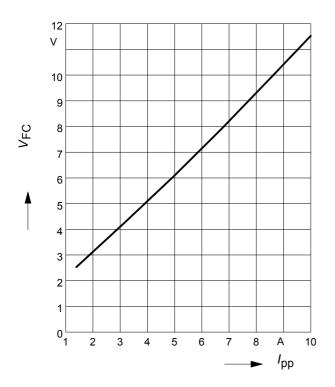
³Only valid in rail-to-rail configuration $V_{CC} \ge V_{RWM}$

⁴Total capacitance line to ground (2 diodes in parallel)



Forward clamping voltage $V_{FC} = f(I_{PP})$

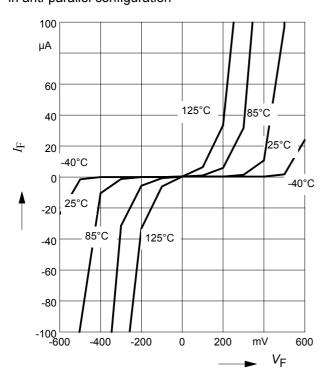
$$t_{\rm p}$$
 = 8 / 20 $\mu {\rm s}$



Forward current $I_F = f(V_F)$

T_A = Parameter

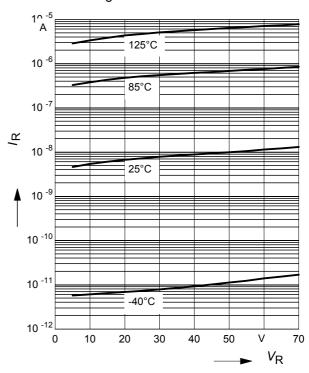
in anti-parallel configuration



Reverse current $I_R = f(V_R)$

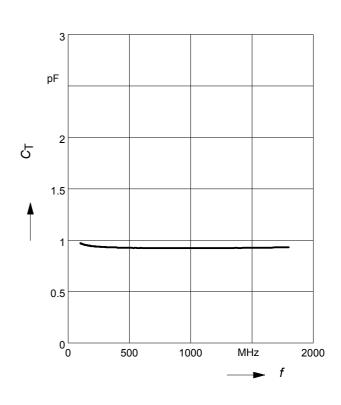
T_A = Parameter

in rail-to-rail configuration



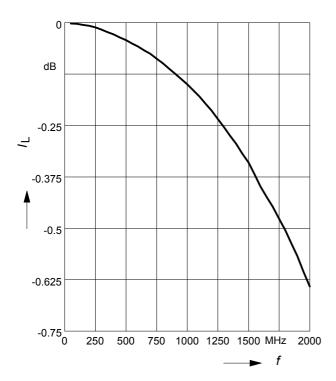
Line capacitance $C_T = f(f)$

$$V_R = 0 V$$





Insertion loss $|S_{21}|^2 = f(f)$ $V_R = 0$ V, line to ground, $Z = 50 \Omega$

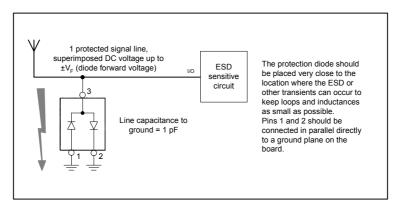


4 =



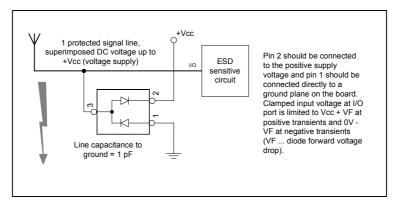
1. Application example ESD1P0RFW

1 channel, anti-parallel configuration



2. Application example ESD1P0RFW

1 channel, rail-to-rail configuration



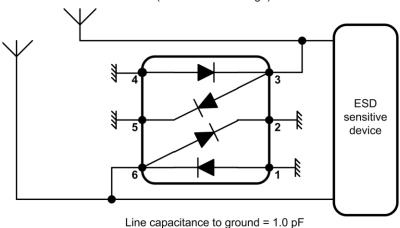
5 =



3. Application example ESD1P0RFS

2 channel, anti-parallel configuration

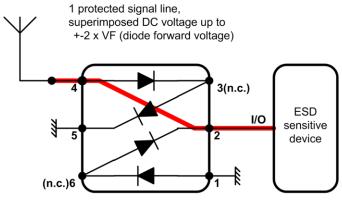
2 protected signal lines, superimposed DC voltage up to +-VF (diode forward voltage)



Pins 1, 2 and 4, 5 should be connected in parallel directly to a ground plane on the board. Clamped input voltage at I/O port is limited to ± VCL (clamping voltage) at positive resp. negative transients.

4. Application example ESD1P0RFS

1 channel, low capacitance anti-parallel configuration



Line capacitance to ground = 0.5 pF

Pins 1 and 5 should be connected directly to a ground plane on the board. Pins 3, 6 are not connected. Clamped input voltage at I/O port is limited to +- 2 x VCL (clamping voltage) at positive resp. negative transients.

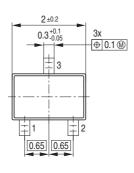
RF line on PCB

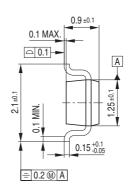




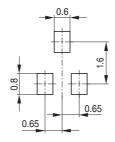
Package Outline



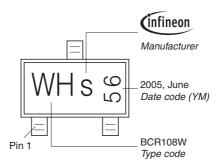




Foot Print

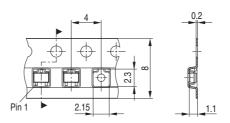


Marking Layout (Example)



Standard Packing

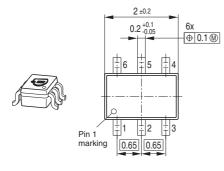
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

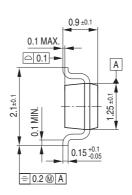




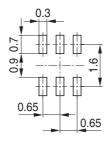


Package Outline



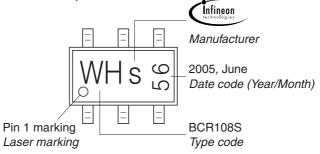


Foot Print



Marking Layout (Example)

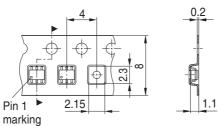
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.





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